



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE6250G V33			<b>Issued</b>	28. August 2013			
<b>MA#</b>	MA000977640							
<b>Package</b>	PG-DSO-8-16			<b>Weight*</b>	83.54 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.700	4.43	4.43	44291	44291
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8585	
wire	non noble metal	copper	7440-50-8	29.121	34.86	35.77	348588	357709
	noble metal	gold	7440-57-5	0.106	0.13	0.13	1265	1265
	encapsulation	organic material	carbon black	1333-86-4	0.094	0.11		1120
plastics	plastics	epoxy resin	-	4.306	5.15		51540	
	inorganic material	silicondioxide	60676-86-0	42.401	50.76	56.02	507552	560212
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9742	9742
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7784	7784
glue	plastics	acrylic resin	-	0.349	0.42		4179	
	noble metal	silver	7440-22-4	1.238	1.48	1.90	14818	18997
*deviation	< 10%			Sum in total:		100,00		1000000

### Important Remarks:

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